



Material Content Data Sheet



Sales Product Name		BTT6010-1EKB		Issued		12. November 2015			
MA#		MA001390614							
Package		PG-DSO-14-47		Weight*		151.04 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.709	3.12	3.12	31180	31180	
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		114		
		non noble metal	zinc	7440-66-6	0.069	0.05		458	
		non noble metal	iron	7439-89-6	1.383	0.92		9160	
wire	non noble metal	non noble metal	copper	7440-50-8	56.175	37.19	38.17	371929	381661
		non noble metal	copper	7440-50-8	0.760	0.50	0.50	5033	5033
		encapsulation	organic material	carbon black	1333-86-4	0.165	0.11		1094
encapsulation	plastics	epoxy resin	-	7.603	5.03		50342		
		inorganic material	silicondioxide	60676-86-0	74.878	49.58	54.72	495758	547194
leadfinish	non noble metal	tin	7440-31-5	2.503	1.66	1.66	16569	16569	
plating	noble metal	silver	7440-22-4	1.470	0.97	0.97	9735	9735	
glue	plastics	epoxy resin	-	0.228	0.15		1510		
		noble metal	silver	7440-22-4	1.075	0.71	0.86	7118	8628
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com